FAIRCHILD SEMICONDUCTOR®

December 2011

FDMC8321L

N-Channel Power Trench® MOSFET

40 V, 49 A, 2.5 mΩ

Features

- Max $r_{DS(on)}$ = 2.5 mΩ at V_{GS} = 10 V, I_D = 22 A
- Max $r_{DS(on)}$ = 4.1 mΩ at V_{GS} = 4.5 V, I_D = 18 A
- Advanced Package and Silicon combination for low $r_{DS(on)}$ and hign efficiency
- Next Generation enhanced body diode technology, engineered for soft recovery
- 100% UIL tested
- RoHS Compliant

General Description

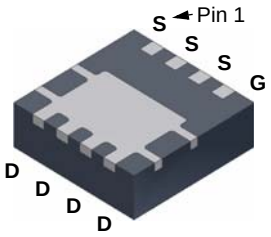
This N-Channel MOSFET has been designed specifically to improve the overall efficiency and to minimize switch node ringing of DC/DC converters using either synchronous or convertional switching PWM contollers. It has been optimized for low gate charge, low $r_{DS(on)}$, fast switching speed body diode reverse recovery performance.

Applications

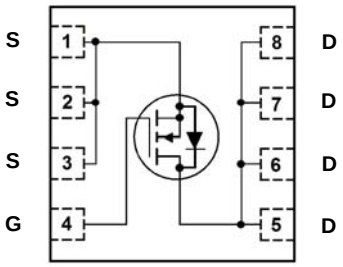
- Synchronous rectifier
- Load switch/Orring
- Motor switch

Top

Bottom



Power 33



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter				Ratings	Units
V_{DS}	Drain to Source Voltage				40	V
V_{GS}	Gate to Source Voltage				±20	V
I_D	Drain Current	-Continuous (Package limit)	T_C = 25 °C		49	A
		-Continuous (Silicon limit)	T_C = 25 °C		100	
		-Continuous	T_A = 25 °C	(Note 1a)	22	
		-Pulsed			100	
E_{AS}	Single Pulse Avalanche Energy			(Note 3)	86	mJ
P_D	Power Dissipation		T_C = 25 °C		40	W
	Power Dissipation		T_A = 25 °C	(Note 1a)	2.3	
T_J, T_{STG}	Operating and Storage Junction Temperature Range				-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	3.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	53	

Package Marking and Ordering Information

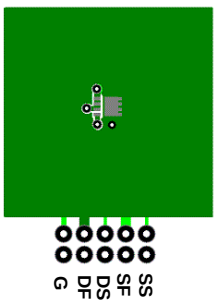
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC8321L	FDMC8321L	Power33	13 ”	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

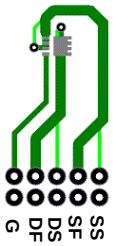
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 μA, V_{GS} = 0 V	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		22		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 32 V, V_{GS} = 0 V			1	μA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0 V			±100	nA
On Characteristics						
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 μA	1	1.7	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		-5		mV/°C
$r_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 22 A		1.9	2.5	mΩ
		V_{GS} = 4.5 V, I_D = 18 A		2.7	4.1	
		V_{GS} = 10 V, I_D = 22 A, T_J = 125 °C		2.8	3.7	
g_{FS}	Forward Transconductance	V_{DS} = 5 V, I_D = 22 A		114		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 20 V, V_{GS} = 0 V, f = 1 MHz		2930	3900	pF
C_{oss}	Output Capacitance			1000	1330	pF
C_{rss}	Reverse Transfer Capacitance			60	90	pF
R_g	Gate Resistance			0.7		Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 20 V, I_D = 22 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		12	22	ns
t_r	Rise Time			6.1	12	ns
$t_{d(off)}$	Turn-Off Delay Time			32	51	ns
t_f	Fall Time			4.9	10	ns
$Q_{g(TOT)}$	Total Gate Charge at 10 V	V_{DD} = 20 V, I_D = 22 A		44	61	nC
$Q_{g(TOT)}$	Total Gate Charge at 5 V			21	32	nC
Q_{gs}	Total Gate Charge			7.7		nC
Q_{gd}	Gate to Drain “Miller” Charge			5.8		nC
Drain-Source Diode Characteristics						
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0 V, I_S = 2 A (Note 2)		0.69	1.2	V
		V_{GS} = 0 V, I_S = 22 A (Note 2)		0.77	1.3	
t_{rr}	Reverse Recovery Time	I_F = 22 A, di/dt = 100 A/μs		41	65	ns
Q_{rr}	Reverse Recovery Charge			20	33	nC

Notes:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



53 °C/W when mounted on a 1 in^2 pad of 2 oz copper



125 °C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.

3.Starting T_J = 25 °C; N-ch: L = 0.3 mH, I_{AS} = 24 A, V_{DD} = 36 V, V_{GS} = 10 V.

Typical Characteristics T_J = 25 °C unless otherwise noted

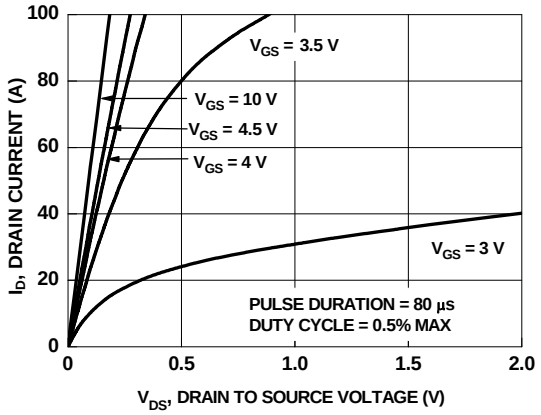


Figure 1. On Region Characteristics

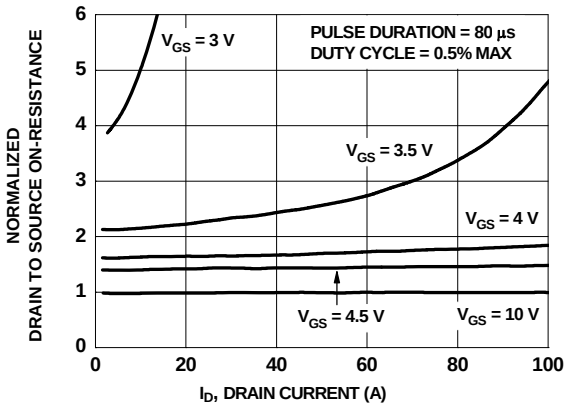


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

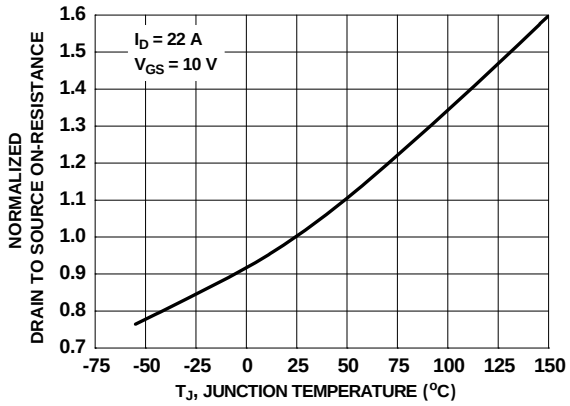


Figure 3. Normalized On Resistance vs Junction Temperature

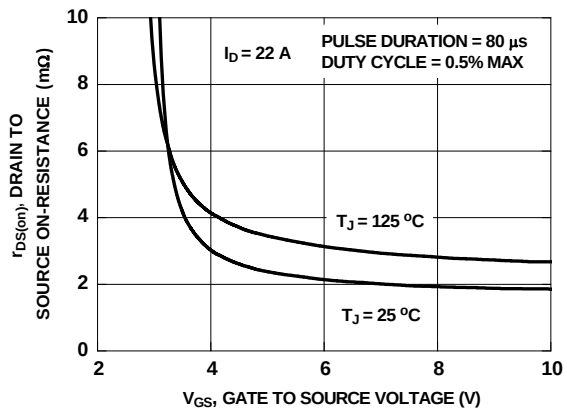


Figure 4. On-Resistance vs Gate to Source Voltage

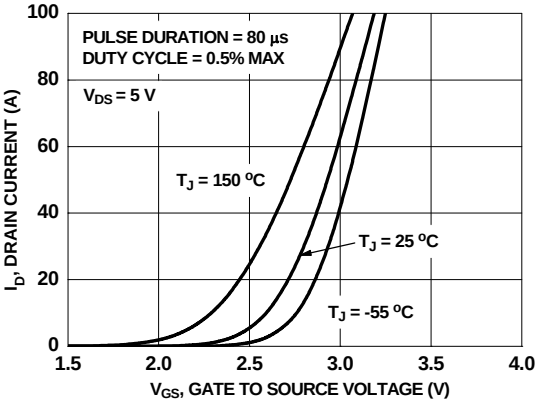


Figure 5. Transfer Characteristics

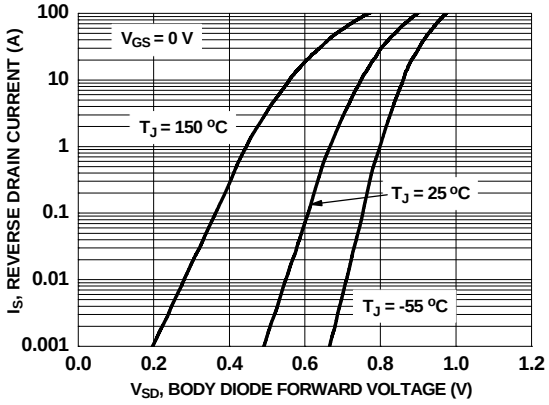


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted

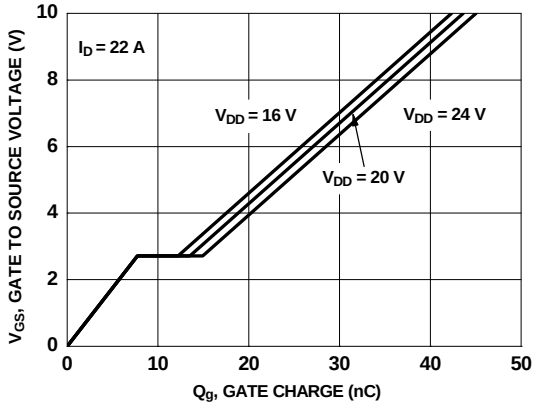


Figure 7. Gate Charge Characteristics

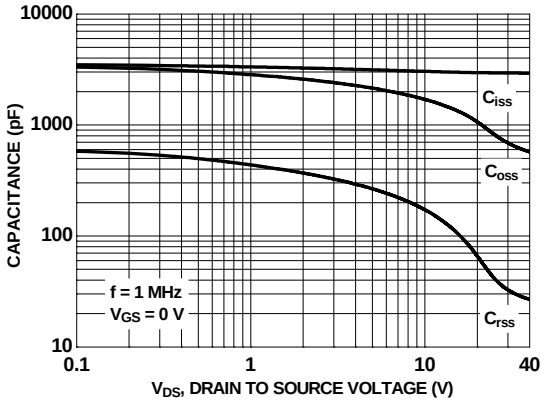


Figure 8. Capacitance vs Drain to Source Voltage

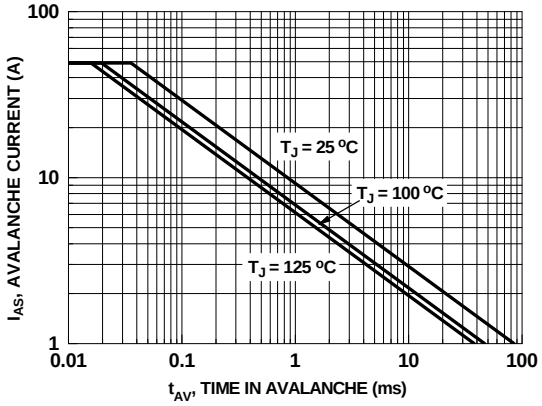


Figure 9. Unclamped Inductive Switching Capability

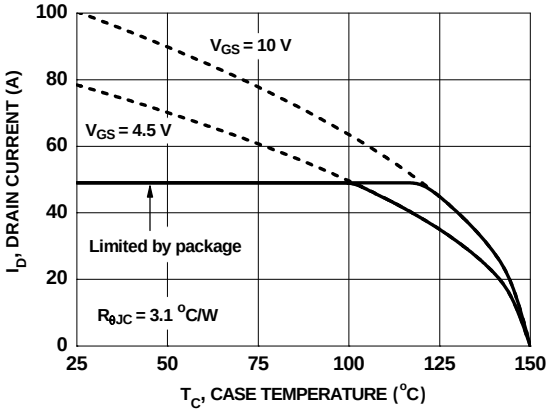


Figure 10. Maximum Continuous Drain Current vs Case Temperature

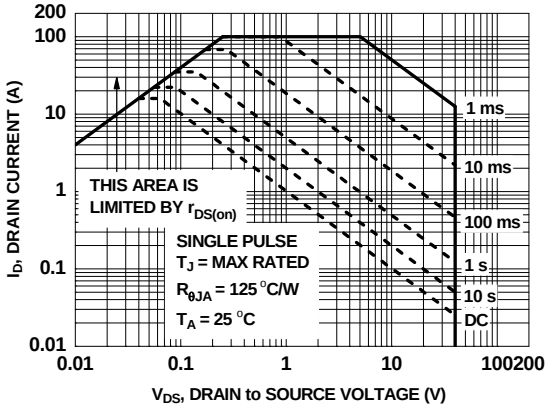


Figure 11. Forward Bias Safe Operating Area

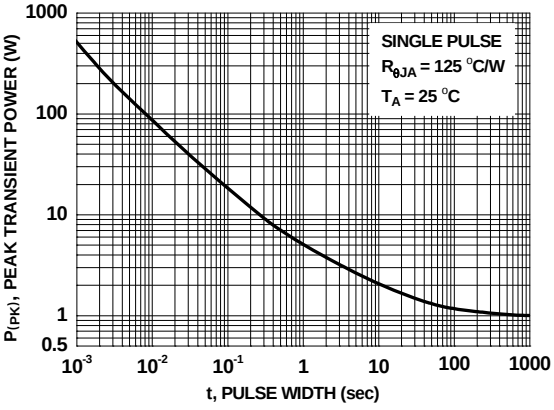


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

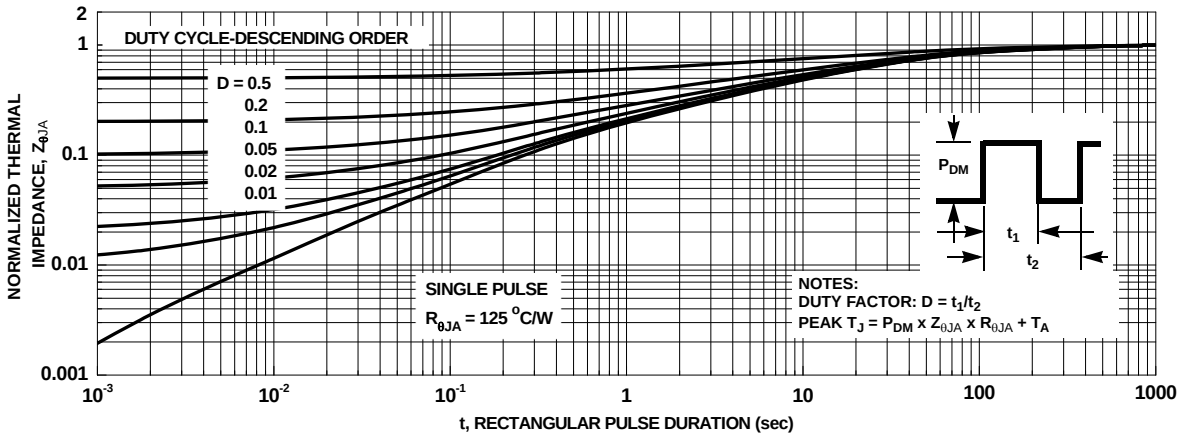
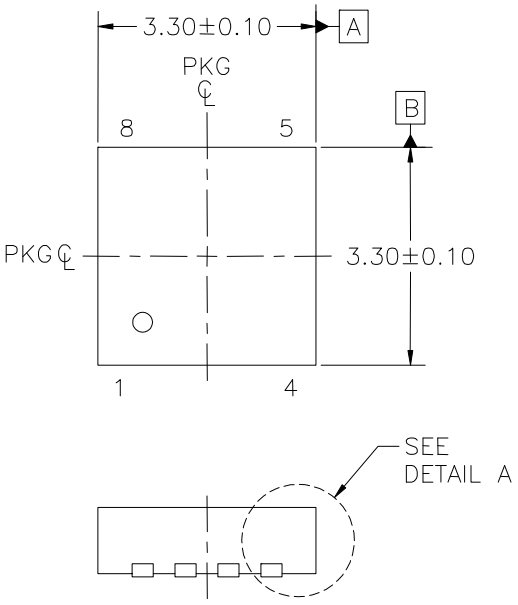
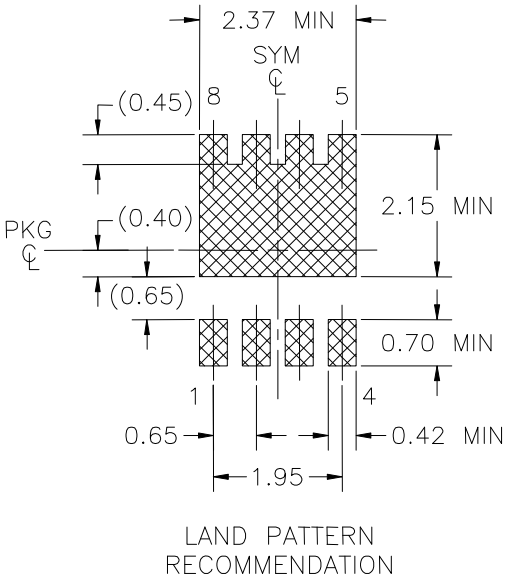


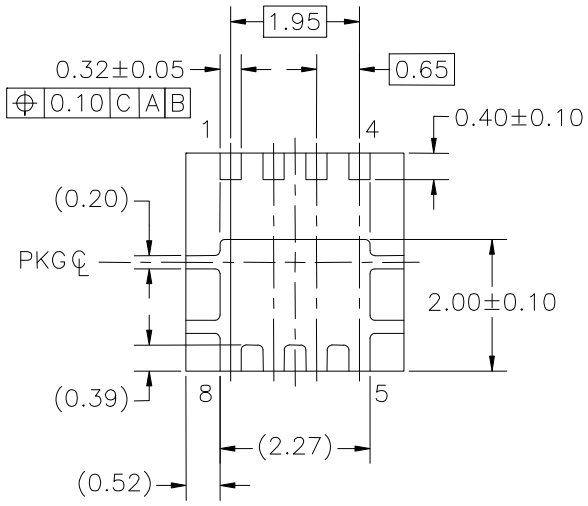
Figure 13. Junction-to-Ambient Transient Thermal Response Curve

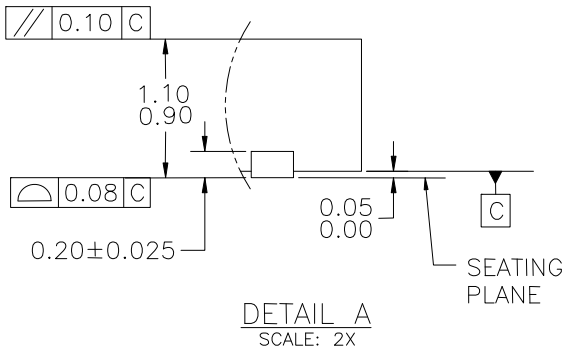
Dimensional Outline and Pad Layout





LAND PATTERN
RECOMMENDATION





DETAIL A
SCALE: 2X

NOTES: UNLESS OTHERWISE SPECIFIED

A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
E) DRAWING FILE NAME: PQFN08BREV1

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